

**Electronic Filing System (EFS) Data**  
**Electronic Patent Application Submission**  
**USPTO Use Only**

EFS ID: 57249

Application ID: 10708649



Title of Invention: METHOD FOR FORMING ROBUST  
SOLDER INTERCONNECT  
STRUCTURES BY REDUCING  
EFFECTS OF SEED LAYER  
UNDERETCHING

First Named Inventor: Kamalesh Srivastava

Domestic/Foreign Application: Domestic Application

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